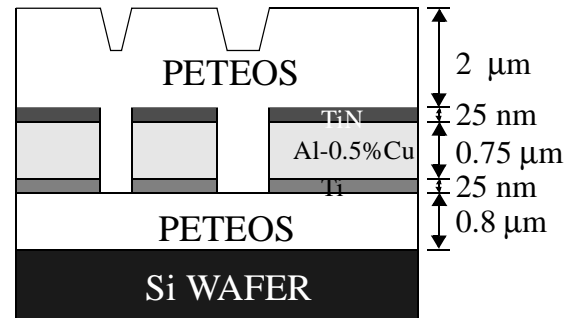
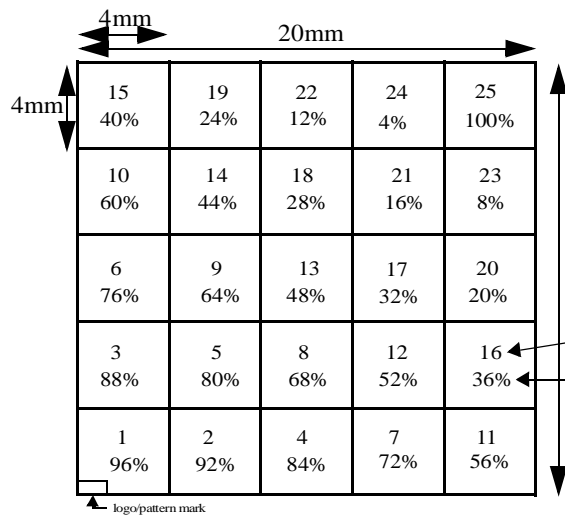


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# SKW1-1 150mm Wafer Specifications

DATE: November 30, 2001



Structure No. →  
 Pattern Density =  $\frac{L_w}{L_w + L_s}$

**SKW1 Density Mask Floor Plan & Cross Section View**

PARAMETER	NOMINAL	TOLERANCE
<b><i>Patterning</i></b>		
Center Die X Location	-10.000 mm	+/- 100 $\mu\text{m}$
Center Die Y Location	-10.000 mm	+/- 100 $\mu\text{m}$
Die Size: X	20 mm	+/- 10 $\mu\text{m}$
Die Size: Y	20 mm	+/- 10 $\mu\text{m}$
Die Spacing	120 $\mu\text{m}$	+/- 10 $\mu\text{m}$
<b>Wafers must be patterned all the way to the edges of the wafer, i.e. no area anywhere on wafer unpatterned. (Under certain stepper operating conditions, 2mm or more edge exclusion is allowed.)</b>		
<b><i>Linewidth Variation</i></b> (measured on 10 $\mu\text{m}$ and 90 $\mu\text{m}$ structures)		
Lot-to-Lot	10 $\mu\text{m}$ , 90 $\mu\text{m}$	+/- 1 $\mu\text{m}$
Within-Lot (Wafer-to-Wafer)		+/- 1 $\mu\text{m}$
Within-Wafer		+/- 1 $\mu\text{m}$
Within-Die		+/- 1 $\mu\text{m}$
<b><i>Thickness</i></b>		
Lot-to-Lot	2.0 $\mu\text{m}$	+/- 5%
Within-Lot (Wafer-to-Wafer)		+/- 5%
Within-Wafer		+/- 2%
Within-Die		+/- 2%
<b><i>Step-Height (Trench Depth)</i></b>		
Lot-to-Lot	8000 $\text{\AA}$	+/- 10%
Within-Lot (Wafer-to-Wafer)		+/- 10%
Within-Wafer		+/- 5%
Within-Die		+/- 5%